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Part Number: [0754921047](#)
Status: **Active**
Overview: [gbx_backplane_connector_system](#)
Description: 1.85mm by 1.85mm (.073 by .073") Pitch 2-Pair GbX® Backplane Connector System, Power Module, 4 Circuits, 1.27µm (50µ") Gold (Au)

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-75221-999 \(PDF\)](#)

Agency Certification

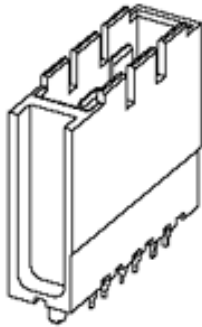
UL E29179

General

Product Family Backplane Connectors
Series [75492](#)
Application Backplane
Application Tooling Documents Tooling Manual
Comments Blade Length A 4.50mm, B 7.50mm
Component Type Power Header
Overview [gbx_backplane_connector_system](#)
Product Name GbX®
Style N/A

Physical

Circuits (Loaded) 4
Circuits (maximum) 4
Circuits Detail Rows A & B
Color - Resin Gray (Dark)
Durability (mating cycles max) 200
First Mate / Last Break Yes
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal High Performance Alloy (HPA)
Material - Plating Mating Gold
Material - Plating Termination Tin-Lead
Material - Resin High Temperature Thermoplastic
Number of Columns N/A
Number of Pairs 2
Number of Rows 2
Orientation Vertical
PC Tail Length (in) 0.090 In
PC Tail Length (mm) 2.28 mm
PCB Locator Yes
PCB Retention Yes
PCB Thickness Recommended (in) 0.063 In
PCB Thickness Recommended (mm) 1.60 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.730 In
Pitch - Mating Interface (mm) 1.85 mm
Pitch - Term. Interface (in) 0.102 In
Pitch - Term. Interface (mm) 2.60 mm
Plating min: Mating (µin) 50
Plating min: Mating (µm) 1.25



Series
image - Reference only

EU RoHS
RoHS Compliant by Exemption
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Halogen-Free

China RoHS



Pb

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[75492Series](#)

Mates With
[75292 GbX® Daughtercard](#)

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Description	Product #
GbX® Shield Removal Tool	0622022100
GbX® 2 Pair 1-Up Power Module	0622022480

Plating min: Termination (μin)	30
Plating min: Termination (μm)	0.75
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	6A
Data Rate	8.0 Gbps
Shielded	No
Voltage - Maximum	120V AC (RMS)/DC

Material Info

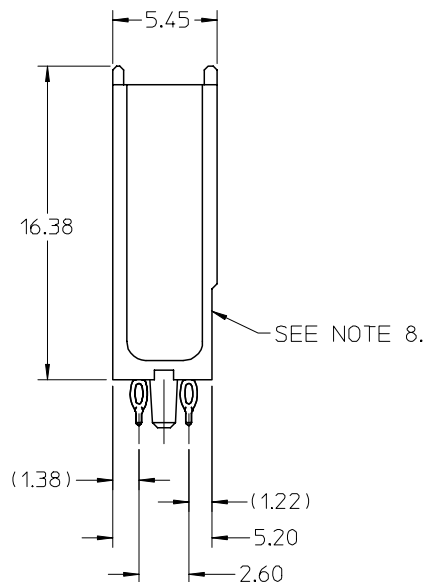
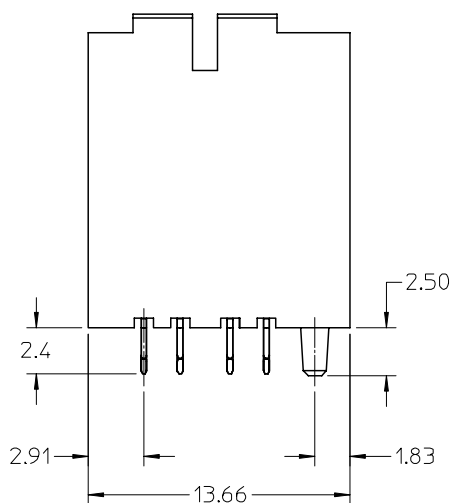
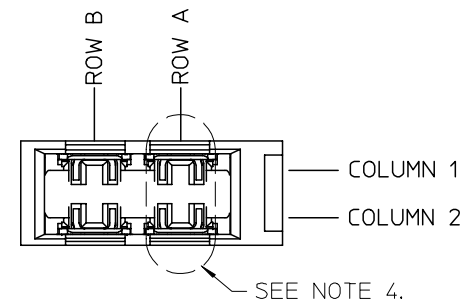
Reference - Drawing Numbers

Packaging Specification	PK-70873-578
Product Specification	PS-75221-999
Sales Drawing	SD-75492-001

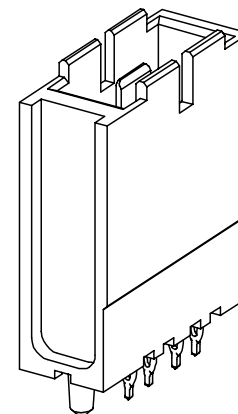
GbX is a registered trademark of Amphenol Corporation.

This document was generated on 05/25/2010
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10 9 8 7 6 5 4 3 2 1



- NOTES:
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, GRAY; CONTACT - COPPER ALLOY
 2. FINISH: SELECT GOLD IN CONTACT AREA, 50 μ THICK; TIN/LEAD OR MATTE TIN IN COMPLIANT AREA.
 3. PACKAGING PER PK-70873-578.
 4. CONTACTS IN EACH ROW HAVE THE SAME WIPE LENGTH.
 5. BACKPLANE ASSEMBLY MATES WITH DAUGHTERCARD POWER MODULE 75292-2***.
 6. PART SHOWN IS 75492-1067.
 7. SEE OTHER SHEETS FOR ADDITIONAL NOTES.
 8. WHEN INSERTING OPEN SIGNAL MODULES NEXT TO COLUMN 1 SIDE OF POWER MODULES, SIGNAL MODULES MUST BE INSERTED BEFORE THE POWERS TO AVOID INTERFERENCE BETWEEN THE TWO CONNECTOR HOUSINGS.
 9. THESE PARTS CONFORM TO MOLEX PRODUCT SPECIFICATION PS-75221-999.
 10. THESE PARTS CONFORM TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS B.



1-UP ASSEMBLY PART NUMBER

7 5 4 9 2 - 1 0 A B

- TIN/LEAD PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:

4 = 4.5 mm

6 = 6.0 mm

7 = 7.5 mm

- LEAD-FREE PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:

2 = 4.5 mm

3 = 6.0 mm

5 = 7.5 mm

SEE SHEET 4 FOR HOLE PATTERN LAYOUT

ADDED NOTES 9 & 10 EC NO: UCP2008-0426 DRAWN: STEWART 2007/08/29 CHKD: J. BINGHAM 2007/08/30 APPR: J. BINGHAM 2007/08/31	QUALITY SYMBOLS =0 =0	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY ELO	DATE 2005/07/01	TITLE GBX 2 PAIR BACKPLANE POWER SALES ASSEMBLY		
			4 PLACES	± ---	± ---	CHECKED BY	DATE 2005/07/01			
			3 PLACES	± ---	± ---	ELO	2005/07/01			
			2 PLACES	± ---	± ---	APPROVED BY	DATE 2005/07/06			
			1 PLACE	± ---	± ---	BIXLER	2005/07/06	MOLEX INCORPORATED		
			ANGULAR ± 5 °		MATERIAL NO.	DOCUMENT NO.	SHEET NO. 1 OF 4			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-75492-001			

9 8 7 6 5 4 3 2 1

2-UP ASSEMBLY PART NUMBER

7 5 4 9 2 - 2 0 A B

- TIN/LEAD PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:

4 = 4.5 mm

6 = 6.0 mm

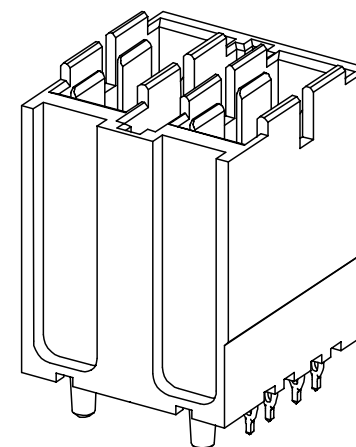
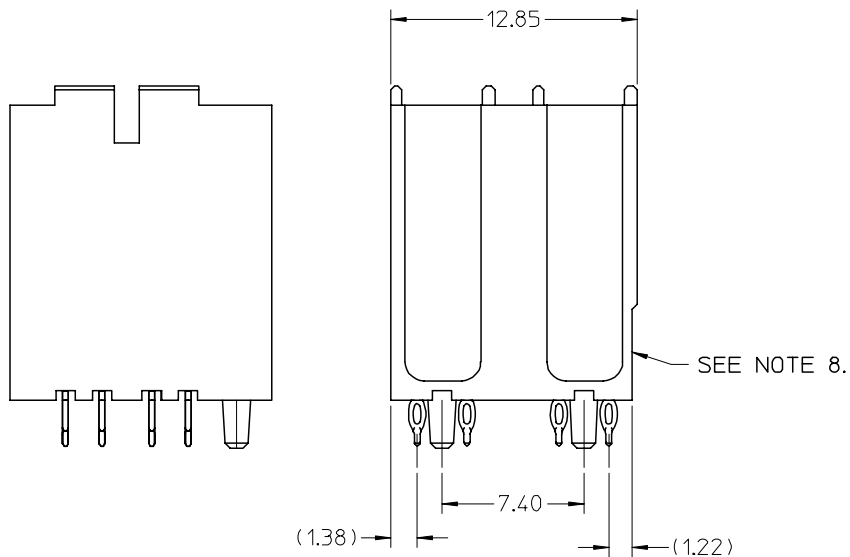
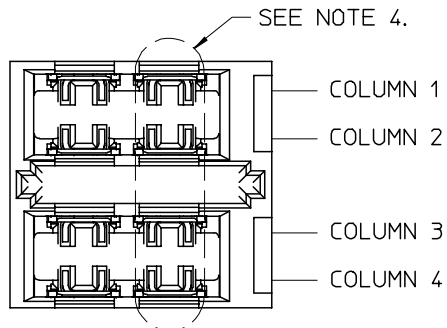
7 = 7.5 mm

- LEAD-FREE PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:

2 = 4.5 mm

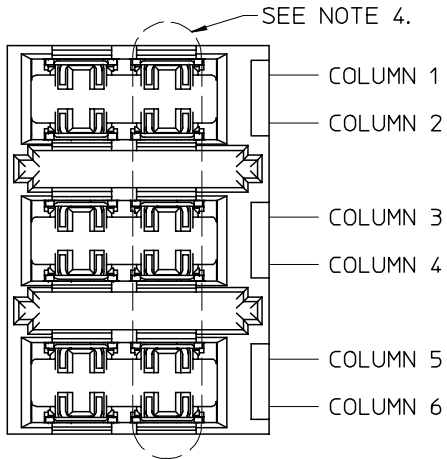
3 = 6.0 mm

5 = 7.5 mm



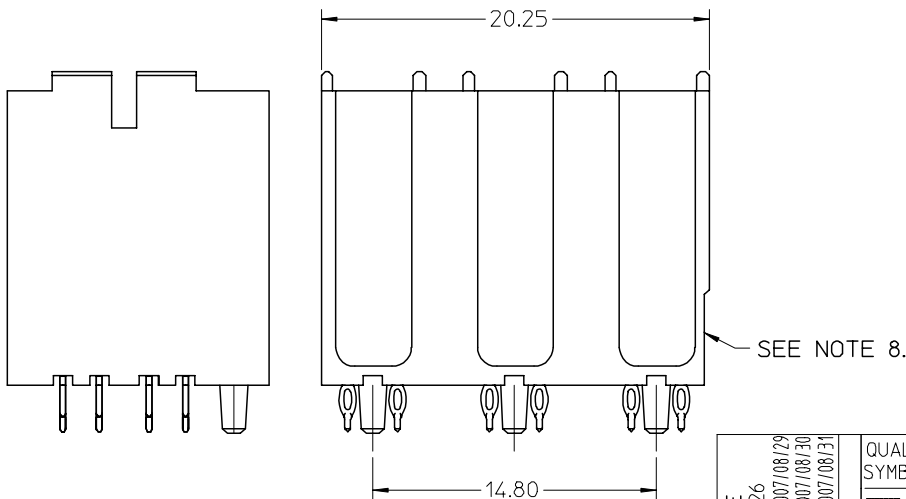
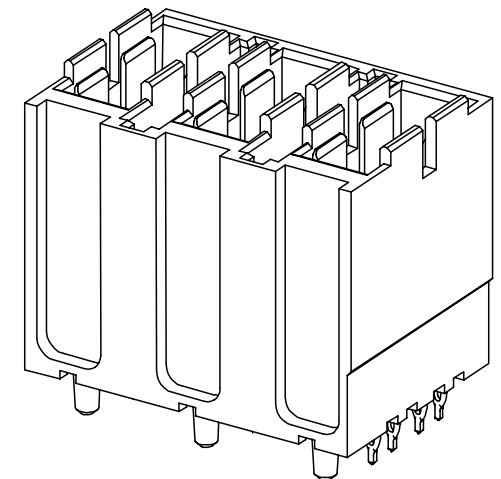
SEE SHEET 1 FOR ADDITIONAL INFORMATION
CHECK WITH PRODUCT MANAGER FOR AVAILABILITY

SEE SHEET ONE EC NO: UCP2008-0426 DRWN: STEWART 2007/08/29 CHKD: J. BINGHAM 2007/08/30 APPR: J. BINGHAM 2007/08/31	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY ELO	DATE 2005/07/01	TITLE GBX 2 PAIR BACKPLANE POWER SALES ASSEMBLY MOLEX INCORPORATED	
			4 PLACES	± ---	± ---	CHECKED BY	DATE		
			3 PLACES	± ---	± ---	ELO	2005/07/01		
			2 PLACES	± ---	± ---	APPROVED BY	DATE		
			1 PLACE	± ---	± ---	BIXLER	2005/07/06		
			ANGULAR ± 5 °		MATERIAL NO.	DOCUMENT NO.	SHEET NO. 2 OF 4		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-75492-001		
			SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



3-UP ASSEMBLY PART NUMBER

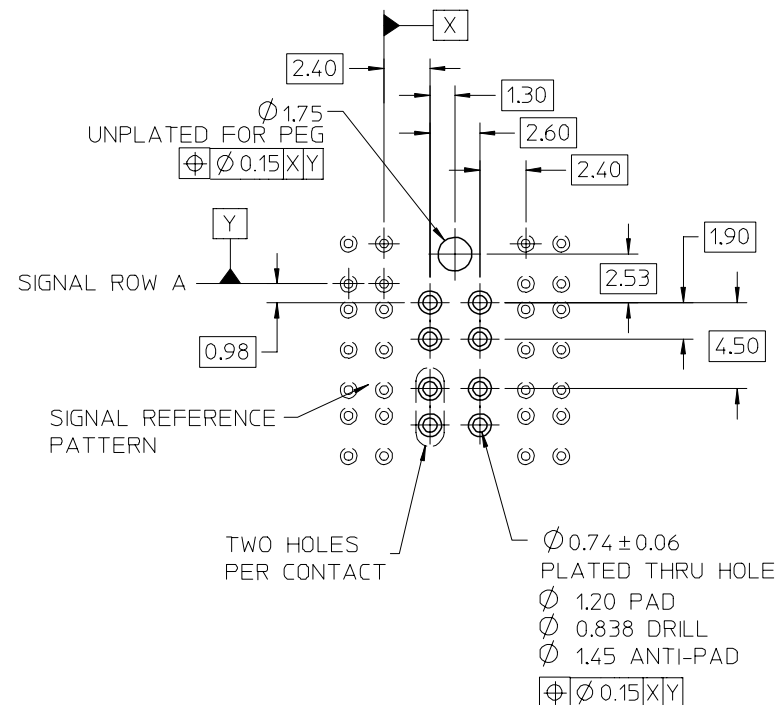
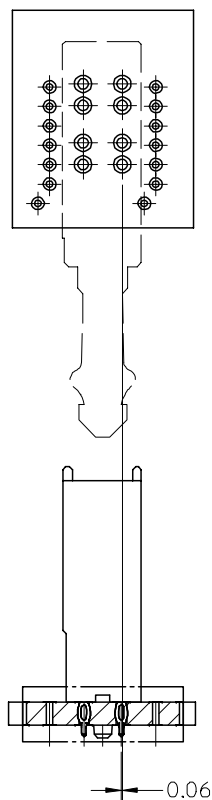
- 7 5 4 9 2 - 3 0 A B
- TIN/LEAD PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:
4 = 4.5 mm
6 = 6.0 mm
7 = 7.5 mm
 - LEAD-FREE PLATED PRODUCT -
FOR EACH ROW LOCATION A, B:
2 = 4.5 mm
3 = 6.0 mm
5 = 7.5 mm



SEE SHEET 1 FOR ADDITIONAL INFORMATION
CHECK WITH PRODUCT MANAGER FOR AVAILABILITY

SEE SHEET ONE EC NO: UCP2008-0426 DRAWN: STEWART 2007/08/29 CHKD: BINGHAM 2007/08/30 APPR: BINGHAM 2007/08/31	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
					DRAWN BY ELO	DATE 2005/07/01	TITLE GBX 2 PAIR BACKPLANE POWER SALES ASSEMBLY		
					CHECKED BY ELO	DATE 2005/07/01			
					APPROVED BY BIXLER	DATE 2005/07/06			
			ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		
REV C		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE CHART		SD-75492-001				
			SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

- 1.) ADD 7.40 FROM CENTERLINES OF PEG FOR MULTIPLE UP ASSEMBLIES
- 2.) USE 5.55 FROM CENTERLINE TO CENTERLINE OF PEG
FOR INDIVIDUAL POWER MODULES STACKED NEXT
TO EACH OTHER.



ib_frame_B_P_AM_T
Rev. E 2006/04/15

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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